

ABSTRACT

The present invention is related to a method for producing micromachined devices for use in Microelectromechanical Systems (MEMS), comprising the steps of

5 providing a crystalline wafer, and processing from said wafer at least one micromachined device comprising at least one elongated opening and/or cavity, having a longitudinal axis, so that said longitudinal axis is at an angle to a direction which lies along the intersection of the front plane of the wafer and a cleavage plane, said cleavage plane being defined as a plane along which cleavage of the wafer is most likely to

10 occur.

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